

SOT879-2

LPGA196, plastic, low profile ball grid array; 196 balls; 1 mm pitch; 15 mm x 15 mm x 1.16 mm body

11 September 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LPGA196
Package style descriptive code	LPGA (low profile ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	24-12-2015
Manufacturer package code	98ARH98217A

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	15	-	mm
package width	-	15	-	mm
package height	-	1.16	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	196	-	



LPGA196, plastic, low profile ball grid array; 196 balls; 1 mm pitch; 15 mm x 15 mm x 1.16 mm body

2 Package outline

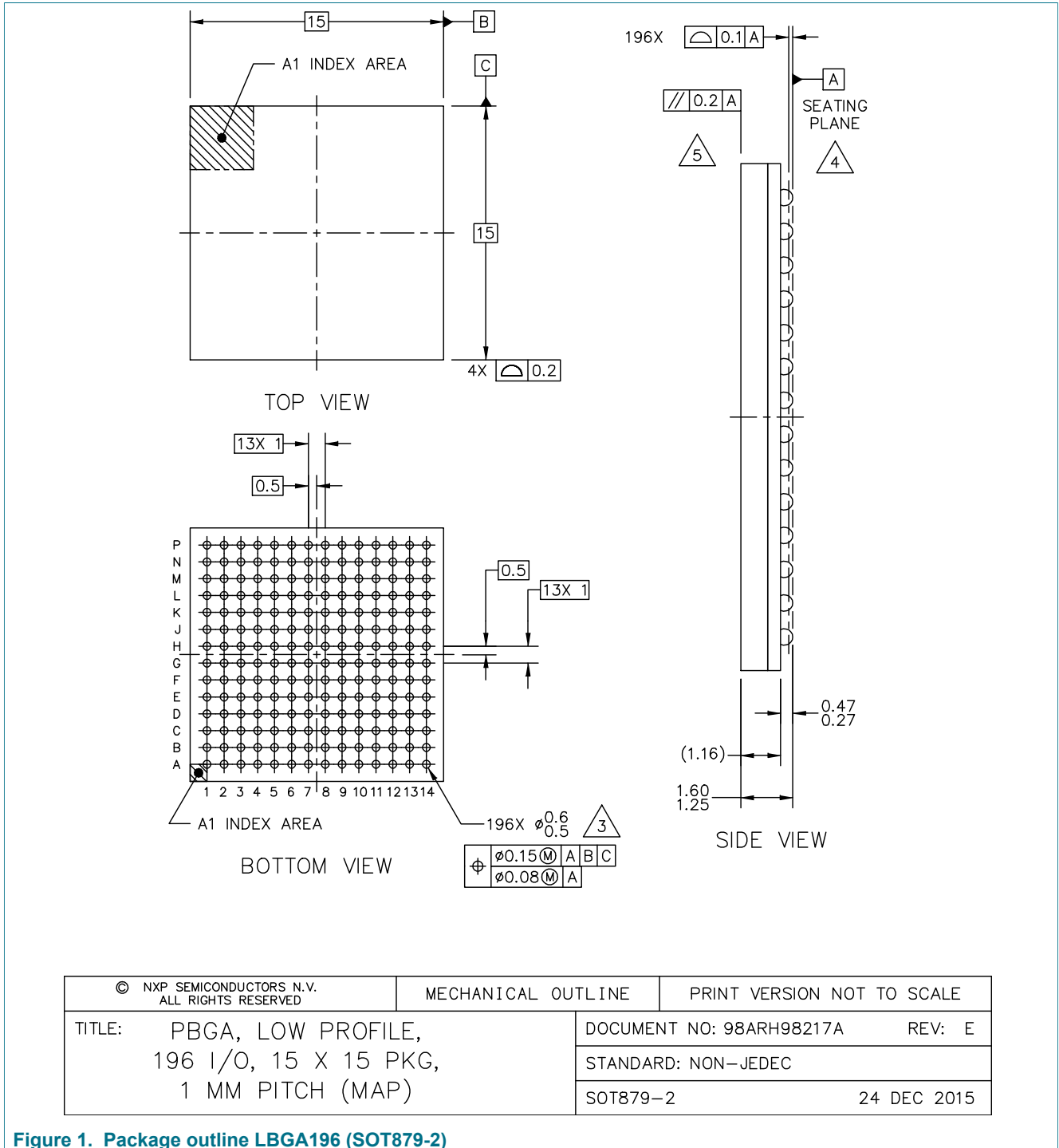


Figure 1. Package outline LPGA196 (SOT879-2)

LPGA196, plastic, low profile ball grid array; 196 balls; 1 mm pitch; 15 mm x 15 mm x 1.16 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: PBGA, LOW PROFILE, 196 I/O, 15 X 15 PKG, 1 MM PITCH (MAP)	DOCUMENT NO: 98ARH98217A	REV: E
	STANDARD: NON-JEDEC	
	SOT879-2	24 DEC 2015

Figure 2. Package outline note LPGA196 (SOT879-2)

3 Legal information

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